

A

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C

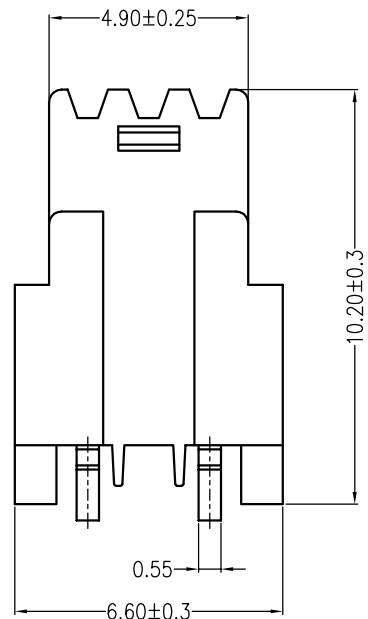
D

E

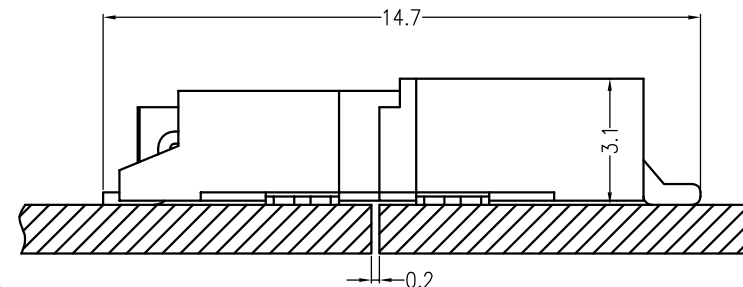
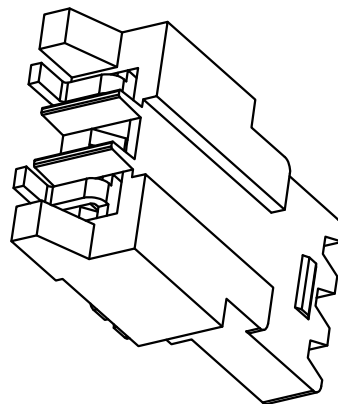
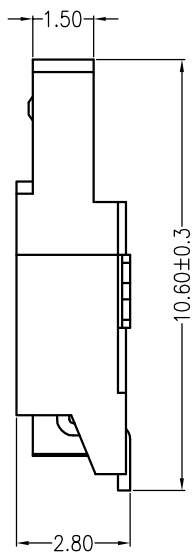
F

REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2015.07.15

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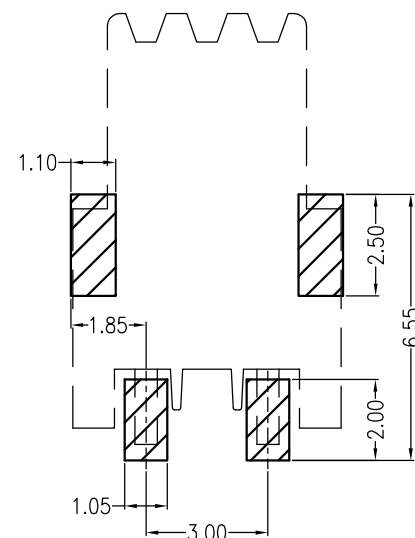
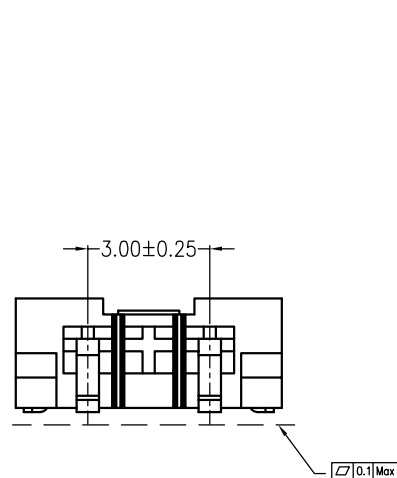
### Assembly Layout

#### 主要技术参数 Main Specifications

线数 (Poles): 02P  
 接触电阻 (Contact resistance):  $\leq 20m\Omega$   
 绝缘电阻 (Insulation resistance):  $\geq 1000M\Omega$   
 额定电压 (Rated voltage): 150 V AC DC  
 额定电流 (Rated current): 1.0A AC DC  
 耐电压 (Withstand Voltage): 1000V AC/minute  
 温度范围 (Temperature Range):  $-25^{\circ}C \sim +105^{\circ}C$

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#### Board Layout

General Tolerance:  $\pm 0.05$

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ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	Solder Tab	2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

NINGBO KLS ELECTRONIC CO.,LTD

TITLE: -  
3.0mmPITCH 90°WAFER SMT TYPE

X.±0.5	X.±5'	USE: CUSTOMER	PART NO.: L-KLS2-L95A-02	
.X±0.3	.X±2'		DWG NO.:	
.XX±0.25	.XX±1'	APPD: 邵敬和	SCALE	
--	--	CHKD: 田峰	1 : 1	SHEET
⊕	∠	UNITS: mm	DR: 吴丹平	1 / 1

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